



ocket No. 884.159US2

Client Ref. No. P7339C

## CLEAN VERSION OF PENDING CLAIMS

### CHIP PACKAGE WITH DEGASSING HOLES

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30. (Amended) An integrated circuit package comprising:

a first conductive layer having a first grid of holes disposed relative to a first coordinate system;

a second conductive layer parallel to the first conductive layer, the second conductive layer having a second grid of holes offset from the first grid of holes and disposed relative to the first coordinate system;

a dielectric layer between the first and second conductive layers; and

at least one conductive signal trace disposed within the dielectric layer, the at least one conductive signal trace disposed parallel to an axis of a second coordinate system that is rotated with respect to the first coordinate system by an angle of between zero and forty-five degrees.

35. (Amended) The integrated circuit package of claim 34 wherein the at least one conductive signal trace includes at least one segment rotated substantially 22.5 degrees relative to the first coordinate system.

37. (Amended) The integrated circuit package of claim 30 wherein the first grid of holes includes holes spaced with non-equal pitch in an x direction and in a y direction relative to the first coordinate system.

39. An integrated circuit package comprising:

a core having first and second sides; and

built-up layers on the first side of the core, the built-up layers including first and second conductive layers with non-aligned grids of degassing holes.

40. The integrated circuit package of claim 39 further comprising a signal layer between the first and second conductive layers, the signal layer including at least one signal trace with segments rotated relative to the grids of degassing holes.
41. The integrated circuit package of claim 39 further comprising built-up layers on the second side of the core, the built-up layers on the second side of the core including third and fourth conductive layers with non-aligned grids of degassing holes.
42. The integrated circuit package of claim 39 wherein:  
the first conductive layer includes a first grid of degassing holes arranged in an x direction and a y direction; and  
the second conductive layer includes a grid of degassing holes offset from the first grid of degassing holes in at least one of the x direction and the y direction.
43. The integrated circuit package of claim 39 wherein:  
the first conductive layer includes a first grid of degassing holes arranged in an x direction and a y direction; and  
the second conductive layer includes a grid of degassing holes offset from the first grid of degassing holes in both the x direction and the y direction.
44. The integrated circuit package of claim 43 further comprising:  
a signal layer between the first and second conductive layers, the signal layer including at least one trace segment rotated substantially 22.5 degrees relative to the x direction.
45. The integrated circuit package of claim 44 further comprising built-up layers on the second side of the core, the built-up layers on the second side of the core including third and fourth conductive layers with non-aligned grids of degassing holes.

46. The integrated circuit package of claim 45 wherein:
- the third conductive layer includes a first grid of degassing holes arranged in the x direction and the y direction; and
  - the fourth conductive layer includes a grid of degassing holes offset from the third grid of degassing holes in both the x direction and the y direction.
47. The integrated circuit package of claim 46 further comprising:
- a signal layer between the third and fourth conductive layers, the signal layer including at least one trace segment rotated substantially 22.5 degrees relative to the x direction.